

Metallizing a fluoropolymer substrate for forming conductor structures or a plasma etching mask on a circuit substrate

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Abstract of DE19817388

A fluoropolymer substrate is metallized by arc discharge deposition of a nickel layer, prior to further metallization. A metallized substrate is produced by coating its fluoropolymer surface with a nickel layer by nickel compound decomposition in an arc discharge and then with a metal layer from a metallization bath. An Independent claim is also included for application of the above process to formation of conductor structures or a plasma etching mask on the fluoropolymer surfaces by selective etching or deposition of the metal layers using resists.

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